# **Specification of Thermoelectric Module**

TEC1-12715

# **Description**

The 127 couples, 50 mm × 50 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 70 °C or larger delta T max, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

#### **Features**

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

# **Application**

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

# **Performance Specification Sheet**

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>	
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U <sub>max</sub> (Voltage)	16.0	17.2	Voltage applied to the module at DT <sub>max</sub>	
I <sub>max</sub> (amps)	15.0	15.0	DC current through the modules at DT <sub>max</sub>	
Q <sub>Cmax</sub> (Watts)	150.2	164.2	Cooling capacity at cold side of the module under DT = 0 °C	
AC resistance (ohms)	0.80	0.88	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

## Geometric Characteristics Dimensions in millimeters

# Positive lead wire (Red) 16AWG leads, PVC insulated Negative lead wire (Black) 125 + 1Cold side:To See ordering option 7 See ordering option Hot side:Th See ordering option A

# **Manufacturing Options**

#### A. Solder:

- 1. T100: BiSn (Melting Point=138°C)
- 2. T200: CuSn (Melting Point= 227 °C)

#### B. Sealant:

- 1. NS: No sealing (Standard)
- 2. SS: Silicone sealant
- 3. EPS: Epoxy sealant
- 4. Customer specify sealing

#### C. Ceramics:

- 1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)(AlO)
- 2. Aluminum Nitride (AlN)

## **D. Ceramics Surface Options:**

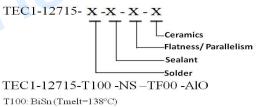
- 1. Blank ceramics (not metalized)
- 2. Metalized (Copper-Nickel plating)

# **Ordering Option**

Suffix	Thickness	Flatness/	Lead wire length(mm)
	(mm)	Parallelism (mm)	Standard/Optional length
TF	0:4.0±0.1	0:0.05/0.05	125±1/Specify
TF	1:4.0±0.05	1:0.025/0.025	125±1/Specify

Eg. TF00: Thickness  $4.0 \pm 0.1$  (mm) and Flatness 0.05 / 0.05 (mm)

# Naming for the Module



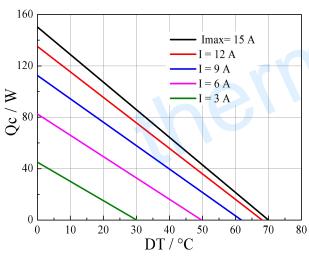
NS: No sealing AlO: Alumina (Al2O3, white 96%) TF00: Thickness ±0.1(mm) and Flatness/Parallelism: 0.05/0.05 (mm)

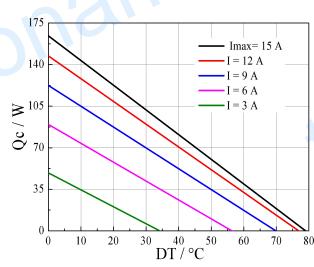
# **Specification of Thermoelectric Module**

## **TEC1-12715**

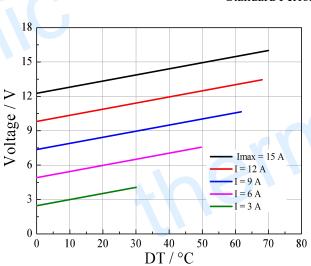


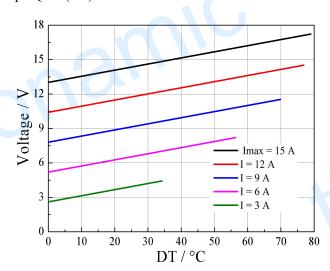
# Performance Curves at Th=50 °C



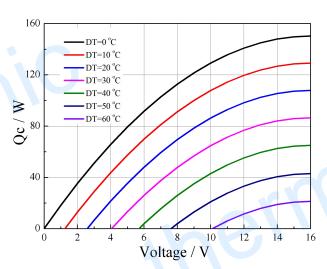


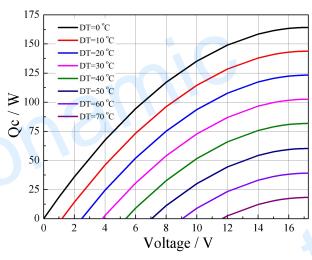
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V = f(DT)

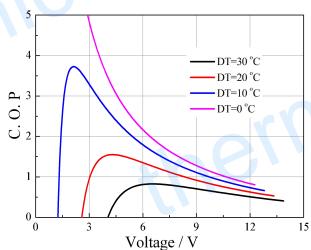




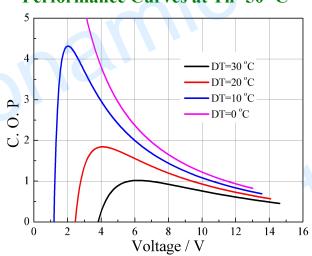
Standard Performance Graph Qc = f(V)

# **Specification of Thermoelectric Module TEC1-12715**

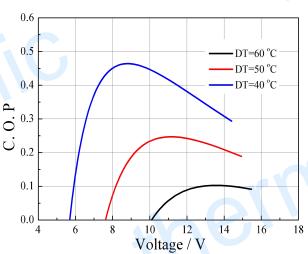


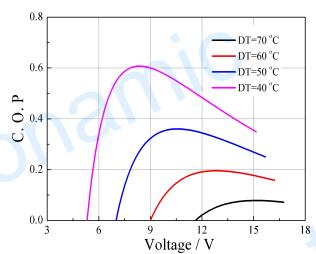


## Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

# **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Storage module below 100°C
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC

Note: All specifications subject to change without notice.